IPC ASSOCIATION ELECTRONIC	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				nder both	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.										ower
1752-21.1					Form Type Distribute						neous Materia	ials and Mfg Information				
Supplie	Information															
Company name*				Company unique ID			Unique ID Authority					Response Date*				
onsemi											2025-09-17					
Contact N	ame	Title - Contact			1	Phone - Contact*					Email - Contact*					
Product-I	Env-Stewards	Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com						
Authorize	d Representative*	Title - Representative			I	Phone - Representative*				Email - Representative*						
Product-I	Env-Stewards	Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com						
	Requester Item Number Mfr Item		Number Mfr Item Name				Effective Date Version Manuf		Manufactu	Ianufacturing Site		Weight*	UOM	Unit Typ	be .	
		FODM3083 4SO RP TRIAC		4SO RP TRIAC			2025-09-17 CP7		CP7		76.835		mg	Each		
Manufa	cturing Proccess Informat	tion						1						,	·	
	Terminal Plating / Grid Array Ma	Terminal Base Alloy J-STD-020 MSI		Rating	Peak Process Body Temper		Body Temperat	ture Max Time at Peak Ter		Temperat	ure Nu	mber of Reflow	Cycles			
	Matte Tin (Sn) - annealed CU A			U Alloy 1			260 C 30			seconds 3						
Comments																
evel 1 - m	aximum time at peak temperatu	re during sol	dering is 10-3	0 seconds												
or more	information regarding material	composition <b>j</b>	please refer to	page 3												

RoHS Material Composition Declaration			Declaration Type *	Detail	ed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU  RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledges and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its paragraph. If the Company and the Supplier supplier has provided certifications of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.											
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the						

## **Homogeneous Material Composition Declaration for Electronic Products**

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

<b>Homogeneous Material</b>	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Coupling Gel	4.9	mg	Supplier	Titanium Dioxide (TiO2)	13463-67-7		2.205	mg
			Supplier	Dimethyl Cyclosiloxanes	69430-24-6		0.49	mg
			Supplier	Trimethoxy(methyl)silane (C4H12O3Si)	1185-55-3		2.205	mg
Die	2.0124	mg	В	Gallium Arsenide (AsGa)	1303-00-0		0.6538	mg
			Supplier	Silicon (Si)	7440-21-3		1.3586	mg
Die Attach	0.17	mg	Supplier	Silver (Ag)	7440-22-4		0.1326	mg
			Supplier	Phenolic Resin-2	54208-63-8		0.0374	mg
Lead Frame	20.6	mg	Supplier	Silver (Ag)	7440-22-4		0.0021	mg
			Supplier	Zinc (Zn)	7440-66-6		0.0247	mg
			Supplier	Iron (Fe)	7439-89-6		0.4738	mg
			Supplier	Copper (Cu)	7440-50-8		20.0932	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0062	mg
Mold Compound-Black	27.9	mg	Supplier	Ortho Cresol Novolac Resin	29690-82-2		3.627	mg
			Supplier	Carbon Black (C)	1333-86-4		0.279	mg
			Supplier	Aluminum Hydroxide (Al(OH)3)	21645-51-2		2.511	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		19.53	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		1.953	mg
Mold Compound-White	21.1	mg	Supplier	Ortho Cresol Novolac Resin	29690-82-2		4.22	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		14.77	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		2.11	mg
Plating	0.1	mg	Supplier	Tin (Sn)	7440-31-5		0.1	mg
Wire Bond - Au	0.053	mg	Supplier	Gold (Au)	7440-57-5		0.053	mg